

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	38	@ad<"20030407" and (adhesive adj tape) with terminal and peel	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 15:36
S4	13	@ad<"20030407" and (adhesive adj tape) with terminal and peel and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 15:37
S14	245	@ad<"20030407" and (tape) with (terminal contact electrode pad) and peel and semiconductor and chip and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 09:43
S15	114	@ad<"20030407" and adhesive with tape with (terminal contact electrode pad) and (wire with bond\$3) and peel\$4 and (semiconductor with chip) and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 11:20
S16	212	@ad<"20030407" and adhesive with tape with (terminal contact electrode pad) and (wire with bond\$3) and TAB and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 08:55
S17	59	@ad<"20030407" and adhesive with tape with (terminal contact electrode pad) same (wire with bond\$3) and TAB and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 10:44
S18	61	@ad<"20030407" and adhesive with tape with (terminal contact electrode pad) same (wire with bond\$3) and (TAB "tape automated bonding") and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 11:29
S32	111	@ad<"20030407" and 257/777, ccls. and (wire with bond\$3) and (reduce with size)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 07:23
S33	13	@ad<"20030407" and 257/777, ccls. and (wire with bond\$3) and (reduce with board with area)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 07:24
S34	19	@ad<"20030407" and adhesive with tape with (terminal contact electrode pad) same (wire with bond\$3) and (TAB "tape automated bonding") and resin and vacuum	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 07:35
S35	0	@ad<"20030407" and adhesive with tape with (terminal contact electrode pad) same (wire with bond\$3) and (TAB "tape automated bonding") and (vacuum with chip with (held hold\$3))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 07:36

EAST Search History

S36	1	@ad<"20030407" and adhesive with tape same (wire with bond\$3) and (TAB "tape automated bonding") and (vacuum with chip with (held hold\$3))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 07:36
S37	62	@ad<"20030407" and (wire with bond\$3) and (TAB "tape automated bonding") and (vacuum with chip with (held hold\$3))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 07:40
S38	9	@ad<"20030407" and (wire with bond\$3) and (TAB "tape automated bonding") and (vacuum with chip with (held hold\$3)) and reel	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 08:06
S39	2	@ad<"20030407" and (wire with bond\$3) and (TAB "tape automated bonding") and (vacuum with tape with (held hold\$3)) and reel	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 11:00
S41	0	(2002/0041019).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/13 14:43
S42	1	2002/0041019	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 11:21
S47	241	@ad<"20030407" and adhesive with tape with (terminal electrode pad) and (TAB "tape automated bonding") and resin and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 11:32
S48	3	@ad<"20030407" and adhesive with tape with (terminal electrode pad) and (TAB "tape automated bonding") and resin and semiconductor and reel and vacuum	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 11:36
S49	7	@ad<"20030407" and adhesive with tape with (terminal electrode pad) and (TAB "tape automated bonding") and resin and semiconductor and reel	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 12:55
S50	37	@ad<"20030407" and adhesive with tape with (terminal electrode pad) and (TAB "tape automated bonding") and reel	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 16:21
S51	47	@ad<"20030407" and (three with layer with tape) and (TAB "tape automated bonding") and reel	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 14:44

EAST Search History

S53	100	@ad<"20030407" and (three with layer with tape) and (TAB "tape automated bonding") and (gold with plat\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 14:45
S54	0	@ad<"20030407" and (three with layer with tape) and (TAB "tape automated bonding") and (gold with plat\$3 with rough)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 14:45
S55	2	@ad<"20030407" and (three with layer with tape) and (TAB "tape automated bonding") and (gold with plat\$3) and rough	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 14:47
S56	0	@ad<"20030407" and (three with layer with tape) and (TAB "tape automated bonding") and (gold with plat\$3) same rough	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 14:46
S57	1	10/510,679	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 14:48
S58	33	@ad<"20030407" and (three with layer with tape) and (TAB "tape automated bonding") and electroless	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/09 14:43
S60	16	@ad<"20030407" and (adhe\$4 with electroless with resin) and TAB	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 15:28
S61	1	@ad<"20030407" and (adhe\$4 with electroless with resin) and rough and TAB	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 15:28
S62	1	@ad<"20030407" and rough adj (terminal electrode pad) and (TAB "tape automated bonding") and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 07:26
S66	21	@ad<"20030407" and (rough with (terminal electrode pad layer) with surface) same resin same plat\$3 same electroless	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 07:53
S67	63	@ad<"20030407" and (adhesive with tape with (chip die) same peel)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 08:56
S77	50	@ad<"20030407" and (adhesive with tape with peel\$4) same (die chip "semiconductor element") same resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 12:11
S78	13	@ad<"20030407" and (adhesive with tape with peel\$4) same (die chip "semiconductor element") same (insulat\$3) and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 12:17

EAST Search History

S79	8	@ad<"20030407" and (adhesive with tape with peel\$4) same (die chip "semiconductor element") and resin and (insulat\$3 with adhesive with (die chip "semiconductor element"))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 12:19
S80	11	@ad<"20030407" and (adhesive with tape with peel\$4) same (die chip "semiconductor element") and resin and (insulat\$3 with (bond\$3 adhesive) with (die chip "semiconductor element"))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 12:19
S81	4	@ad<"20030407" and (adhesive same tape same peel\$4) same (die chip "semiconductor element") and resin and (insulat\$3 adj (bond\$3 adhesive) with (die chip "semiconductor element"))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 13:31
S83	124	@ad<"20030407" and ((double both) adj (side surface) with adhesive with tape) with (die chip "semiconductor element")	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 13:33
S84	1	10/510,679	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/09 13:04
S85	1	"10234019"	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/09 13:09
S86	283	@ad<"20030407" and (TAB "tape automated bonding") and tape with thermocompression	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/09 14:44
S87	153	@ad<"20030407" and (TAB "tape automated bonding") and tape with thermocompression adj bonding	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/09 14:44
S88	12	@ad<"20030407" and (TAB "tape automated bonding") and tape with thermocompression adj bonding with metal	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/09 14:49
S89	4	@ad<"20030407" and (TAB "tape automated bonding") and tape with thermocompression adj bonding same (metal copper) adj foil	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/09 14:50